



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20230112002.1

Qualification of new Fab site (RFAB) using qualified Process Technology, Die Revision, Datasheet update and additional Assembly site/BOM options for select devices

Change Notification / Sample Request

Date: January 12, 2023

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

PCN Team
SC Business Services

20230112002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
UCC28C40DGKR	null
UCC28C41DGKR	null
UCC28C42DGKR	null
UCC28C43DGKR	null
UCC28C44DGKR	null
UCC28C45DGKR	null
UCC38C43DGKR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20230112002.1	PCN Date:	January 12, 2023
Title:	Qualification of new Fab site (RFAB) using qualified Process Technology, Die Revision, Datasheet update and additional Assembly site/BOM options for select devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Apr 12, 2023	Sample requests accepted until:	February 12, 2023*
*Sample requests received after February 12, 2023 will not be supported.			
Change Type:			
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/> Assembly Materials
<input checked="" type="checkbox"/> Design	<input checked="" type="checkbox"/>	Electrical Specification	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/> Test Process
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/> Wafer Bump Process
<input checked="" type="checkbox"/> Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input checked="" type="checkbox"/> Wafer Fab Process
	<input type="checkbox"/>	Part number change	

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of a new fab & process technology (RFAB, LBC9) and assembly (MLA) site/BOM options for selected devices as listed below in the product affected section.

Current Fab Site			New Fab Site		
Fab Site	Process	Wafer Diameter	Fab Site	Process	Wafer Diameter
SFAB	IMP-PWR2	150 mm	RFAB	LBC9	300 mm

The die was also changed as a result of the process change.

Construction Differences are as follows:

What	ASESH	MLA
Mold Compound	SID#EN2000763	4211880
Mount Compound	SID#EY1000063	4147858
Bond wire composition/diameter	Cu/1.0 mil	Cu/0.8 mil
Pin one symbolization	dot	dimple

The associated datasheet changes were notified in a separate Datasheet change notification on 11/18/2022 (Notification# 20221117000.0) as shown below:



UCC28C40, UCC28C41, UCC28C42, UCC28C43, UCC28C44, UCC28C45, UCC38C40, UCC38C41, UCC38C42, UCC38C43, UCC38C44, UCC38C45
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Changes from Revision G (January 2017) to Revision H (September 2022)	Page
• Changed -40°C to 105°C to -40°C to 125°C, and 0°C to 70°C to 0°C to 85°C.....	1
• Removed PDIP package from Device Information.....	1
• Updated T_J range in Device Comparison Table.....	3
• Removed PDIP package from Pin Configuration.....	4
• Removed PDIP package from Absolute Maximum Table.....	5
• Updated Total Power Dissipation values in Absolute Maximum Table.....	5
• Added V_{REF} maximum continuous voltage from external circuitry in Recommended Operating Conditions.....	5
• Updated T_J max values in Recommended Operating Conditions Table.....	5
• Updated all Thermal Resistance Numbers in Thermal Information.....	6
• Updated Electrical Characteristics section	6
• Corrected a drawing error of OUT pin high-side FET connection.....	13

These changes may be reviewed at: <http://www.ti.com/product/UCC28C40>

Tube versions of the devices are included in EOL notice PDN# 20230112005.3.

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-milimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change			

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
RFAB	RFB	USA	Richardson

Die Rev:

Current New

Die Rev [2P]	Die Rev [2P]
A	A

Assembly Site Information:

Assembly Site	Assembly Site Origin Code (22L)	Assembly Country Code (23L)	Assembly City
ASESH	ASH	CHN	Shanghai
MLA	MLA	MYS	Kuala Lumpur

Sample product shipping label (not actual product label):



Product Affected:

UCC28C40DGKR	UCC28C42DGKR	UCC28C44DGKR	UCC38C43DGKR
UCC28C41DGKR	UCC28C43DGKR	UCC28C45DGKR	

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Report
Approve Date 10-January-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: UCC28C41DGKR	Qual Device: UCC28C43DGKR	Qual Device: UCC28C44DGKR	Qual Device: UCC28C44DGKR	QBS Reference: QPA2205ADGKR	QBS Reference: QPA2206ADGKR	QBS Reference: UCC28C44QDRQ1	QBS Reference: LM74700QDBVRQ1	QBS Reference: LM74700QDBVRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	1/77/0	2/154/0	-	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	1/77/0	-	-	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C	96 Hours	-	-	-	-	1/77/0	2/154/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	1/77/0	-	1/77/0	2/154/0	-	-	2/154/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	1/77/0	2/154/0	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	-	-	-	1/45/0
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	1/77/0	2/154/0	-	-	-
HTOL	B1	Life Test	150C	408 Hours	-	-	-	-	-	-	-	1/77/0	2/154/0
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	-	-	1/800/0	2/2000/0	-	-	3/2400/0
ESD	E2	ESD CDM	-	250 Volts	-	-	1/3/0	-	1/3/0	2/6/0	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	1/3/0	2/6/0	1/3/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/6/0	1/6/0	1/6/0	1/6/0	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	-	-	-	-	1/30/0	2/60/0	-	1/30/0	-

- QBS: Qual By Similarity
- Qual Device UCC28C41DGKR is qualified at MSL2 260C
- Qual Device UCC28C43DGKR is qualified at MSL2 260C
- Qual Device UCC28C44DGKR is qualified at MSL2 260C
- Qual Device UCC28C44DGKR is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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